



PCN# : P557AA
Issue Date : Jul. 08, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Oct. 06, 2015

Expected First Date Code of Changed Product :1541

Description of Change (From) :

Wafer fabrication site: 6- inch wafer manufacturing in Fairchild Salt Lake.

Assembly and test site: Fairchild Semiconductor Penang, Malaysia and HANA Ayutthaya, Thailand respectively.

Package	Assembly/DPS Site	Leadframe	Die Attach Material	Wire	Mold Compound
MLP	Fairchild Penang, Malaysia	HaeSung DS RT UPG1 PPF	Henkel QMI-519	1 and 2 mils Au wire	Hitachi CEL9220HF13FC1
Punch MLP	Fairchild Penang, Malaysia	C194 NiPdAu PPF	Henkel QMI-519	2 mils Cu wire	Hitachi CEL9220HF13FC
SO8	Fairchild Penang, Malaysia	ASM bare Cu frame	84-1LMISR4	2 mils Cu wire	Henkel GR828FC1

Description of Change (To) :

Wafer fabrication site: 8- inch wafer manufacturing in Fairchild Bucheon, Korea; and Tower Jazz, Israel.

Assembly and test site: Fairchild Semiconductor Cebu, Philippines and alternate sub- contractor from GEM, China and HANA Ayutthaya, Thailand. No change to current marketing outline specification.

Package	Assembly Site	Leadframe	Die Attach Material	Wire	Mold Compound
MLP	HANA, Thailand	HaeSung DS RT UPG1 PPF	Henkel 8600	1 and 2 mils Au wire	Hitachi CEL9220HF13H
Punch MLP	Fairchild Cebu, Philippines	C194 NiPdAu PPF	Henkel QMI-519	2 mils Cu wire	Hitachi CEL9220HF13FC
SO8	GEM, China	ASM bare Cu frame	Kyocera CT285	2 mils Cu wire	Sumitomo G600FL

Reason for Change:

- Improved supply flexibility.
- Better quality and yields through equipment and facility upgrades.
 - Increased automation in handling and inspection in assembly.
- Fairchild partnerships with foundries and assembly subcontractors.
 - Best manufacturing practices- access to many customer methods and practices.
 - Advanced technology for fast ramp of future new products and technologies.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMS2734	MLDAMC08	Mountain Top UFET Trench	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 42V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMS7620S	MLDAMCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FIN210ACMLX	MLDFL032	Maine FS35C3LMD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Unbias Highly Accelerated Stress Test	85%RH, 130C	JESD22-A110	96 hrs	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FXLA108BQX	MLDFX020	Maine 35CTINYBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 3.6V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDML7610S	MLDEZCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMC86261P	MLDEUC08	Salt Lake MV5 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, -120V	JESD22-A108	1000 hrs	0/77
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
QP13031025 (CP20140002)	FDMS86201	PQFN08A	MV5N/MV5NZ	1

Test Description:	Condition	Standard	Duration	Results:
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, Vr=96V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	Mil Std 750-1036	10000 cyc	0/77
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
QP13031025 (CP20140002)	FDMS86200DC	PQFN08D	MV5N/MV5NZ	3

Test Description:	Condition	Standard	Duration	Result
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=120V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	Mil Std 750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP12120985G (CP20130016)	FDMS0300S	PQFN	N-Channel Power Trench 8 SyncFET	3

Test Description:	Condition	Standard	Duration	Results:
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	Mil Std 750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP13181047 (CP20130033)	FDMS7656AS	PQFN	N-Channel Power Trench 7 SyncFET	3

Test Description:	Condition	Standard	Duration	Results:
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP13011024A (CP20130039)	FDMS7650DC	PQFN_56CLP	PT7 N S	3

Test Description:	Condition	Standard	Duration	Results:
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	175C	JESD22-A103	500 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	Mil Std 750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP13011024A (CP20130039)	FDMC8010	PQFN_33PC	PT8 N S	3

Test Description:	Condition	Standard	Duration	Results:
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	175C	JESD22-A103	500 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	Mil Std 750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20140001	FDMC6676BZ	MLDEUC08	ST3 PZ	3

Test Description:	Condition	Standard	Duration	Results:
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/237
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/237
High Temperature Storage Life	175C	JESD22-A103	500 hrs	0/237
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/237
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/237
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/237

Qualification Pan	Device	Package	Process	No. of Lots
Q20150098	FDMC8884	MLJEUC08	PT4 N-Ch	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A118	96 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20150098	FDMC0310AS_F127	MLDEUC08	PT8 N-SYNCFET	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Highly Accelerated Stress Test	85%RH, 110C, 24V	JESD22-A118	264 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20150098	FDMC86244	MLQEUC08	PT5 N MV	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 120V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Highly Accelerated Stress Test	85%RH, 130C, 42V	JESD22-A118	96 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6910	NMSOD 8L	Salt Lake PT3 N	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS2734	NMSON 8L	Mountain Top UFET TRENCH	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6699S	NMSON 8L	Salt Lake PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6982AS	NMSOD 8L	Mountain Top/Salt Lake PT3 N/PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS8858CZ	NMSOD 8L	Salt Lake PT4 N Z/ST3 P Z	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, Q1:24/Q2:-24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, Q1:20/Q2:-25V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, Q1:24/Q2:-24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140144A	FDS8958A_F085	NMSOD 8L	PT3 N	3

Test Description:	Condition:	Standard:	Duration:	Results:
Preconditioning, MSL 1	260°C, 3 cycles	JESD22-A113	NA	July 22
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 24V	JESD22-A110	96 hrs	July 29
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	Aug 28
High Temperature Reverse Bias	150C, 30V	JESD22-A108	1000 hrs	Aug 28
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	Sep 11
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	Sep 11
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	Aug 23
Unbiased Highly Accelerated Stress Test	85%RH, 130C	JESD22-A118	96 hrs	Jul 29
Resistance to Solder Heat	260°C	JESD22-B106	10 sec	Jul 17
Destructive Physical Analysis (after TMCL)	NA	AEC-Q101-004 Section 4	NA	Sep 7

Qualification Plan	Device	Package	Process	No. of Lots
CP20140019	FDB8132_F085	TO-263	PT4N	3

Test Description:	Condition:	Standard:	Duration:	Results:
Preconditioning, MSL 1	260°C, 3 cycles	JESD22-A113	NA	0/924
Autoclave	121C, 15 psi, 100%RH	JESD22-A102	96 hrs	0/231
H3TRB	85C, 85%RH, 24V	JESD22-A101	1000 hrs	0/231
High Temperature Reverse Bias	175C, 24V	JESD22-A108	1000 hrs	0/231
High Temperature Gate Bias	175C, Vgs 20V	JESD22-A108	1000 hrs	0/231
Power Cycle	T on/off 3 min, 100C Delta	MIL-STD-750-1036	8572 Cycles	0/231
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/231
Resistance to Solder Heat	260C	JESD22-B106	10 sec	0/90

Qualification Plan	Device	Package	Process	No. of Lots
Q20140168	FDB8030L	TO263	PT1 N	3

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22-A113	NA	Jun 23
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 24V	JESD22-A110	96 hrs	Jul 3
High Temperature Gate Bias	175°C, Vgs = 20V	JESD22-A108	1000 hrs	Sep 7
High Temperature Reverse Bias	175°C, Vr = 24V	JESD22-A108	1000 hrs	Sep 7
High Temperature Storage Life	175°C	JESD22-A103	1000 hrs	Aug 17
Power Cycle	Delta 100°C, 3.5 Min cycle	JESD22-A105	8572 cyc	Sep 9
Temperature Cycle	-65°C, 150°C	JESD22-A104	500 cyc	Jul 17
Resistance to Solder Heat	260°C	JESD22-B106	10 sec	Jun 19

Qualification Plan	Device	Package	Process	No. of Lots
Q20140168	FDS6975_SBAM003	SO8	PT1 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22-A113	NA	0/395
Highly Accelerated Stress Test	130°C, 85%RH, Vr = -24V	JESD22-A110	96 hrs	0/79
High Temperature Gate Bias	150°C, Vgs = -20V	JESD22-A108	1000 hrs	0/79
High Temperature Reverse Bias	150°C, Vr = -30V	JESD22-A108	1000 hrs	0/79
High Temperature Storage Life	150°C	JESD22-A103	1000 hrs	0/79
Power Cycle	Delta 100°C, 2 Min cycle	JESD22-A105	15000 cyc	0/79
Temperature Cycle	-55°C, 150°C	JESD22-A104	1000 cyc	0/79
Unbiased Highly Accelerated Stress Test	130°C, 85%RH	JESD22-A118	96 hrs	0/79
Resistance to Solder Heat	260°C	JESD22-B106	10 sec	0/30

Qualification Plan	Device	Package	Process	No. of Lots
Q20140168	FDD3510H	D-PAK	PT1 N and PT1 P	2

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22A-113	NA	0/800
Temperature Cycle	-55°C, 150°C	JESD22-A104	1000 cyc	0/154
High Temperature Storage Life	150°C	JESD22-A103	1000 hrs	0/154
Power Cycle	Delta 100°C, 2 Min On/Off	JESD22-A122	10000 cyc	0/154
Highly Accelerated Stress Test	130°C, 85%RH, 42V	JESD22-A110	96 hrs	0/154
Unbiased Highly Accelerated Stress Test	130°C, 85%RH,	JESD22-A118	96 hrs	0/154
High Temperature Gate Bias	150°C, 20V	JESD22-A108	1000 hrs	0/154
High Temperature Reverse Bias	150°C, 80V	JESD22-A108	1000 hrs	0/154
Resistance to Solder Heat	270°C	JESD22-B106	15 sec	0/10

Qualification Plan	Device	Package	Process	No. of Lots
Q20140168	FDC2612	SSOT6	PT1 N	2

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22-A113	NA	0/616
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 42V	JESD22-A110	96 hrs	0/154
High Temperature Gate Bias	150°C, Vgs = 20V	JESD22-A108	1000 hrs	0/154
High Temperature Reverse Bias	150°C, Vr = 160V	JESD22-A108	1000 hrs	0/154
High Temperature Storage Life	150°C	JESD22-A103	1000 hrs	0/154
Power Cycle	Delta 100CC, 2.0 Min cycle	JESD22-A105	10000 cyc	0/154
Temperature Cycle	-65°C, 150°C	JESD22-A104	500 cyc	0/154
Resistance to Solder Heat	260°C	JESD22-B106	10 sec	0/60